

Title (en)
FLUX FOR RESIN FLUX CORED SOLDERS, FLUX FOR FLUX COATED SOLDERS, RESIN FLUX CORED SOLDER AND FLUX COATED SOLDER

Title (de)
FLUSSMITTEL FÜR HARZFLUSSMITTELGEFÜLLTES LOT, FLUSSMITTEL FÜR FLUSSMITTELBESCHICHTETES LOT, HARZFLUSSMITTELGEFÜLLTES LOT UND FLUSSMITTELBESCHICHTETES LOT

Title (fr)
FLUX DESTINÉ À DES SOUDURE À ÂME DÉCAPANTE DE FLUX RÉSINEUX, FLUX DESTINÉ À DES SOUDURES À ÂME DÉCAPANTE DE FLUX, ET SOUDURE RECOUVERTE DE FLUX

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Application
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Abstract (en)
[origin: EP3456460A1] An object of the present invention is to provide a resin flux cored solder, or a flux coated solder, for which scattering of flux and solder in using the solder is suppressed, and a flux to be contained therein. A flux for a resin flux cored solder comprising a rosin resin, an activator, and at least one selected from an acrylic polymer and a vinyl ether polymer, which has a weight average molecular weight of 8000 to 100000, in an amount of 0.1 to 3 mass-% based on the total mass of the flux.

IPC 8 full level
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Citation (search report)
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• [A] US 2008053572 A1 20080306 - SANJI MASAKI [JP], et al
• [A] EP 2939784 A1 20151104 - HARIMA CHEMICALS INC [JP]
• [A] JP 2015131336 A 20150723 - TAMURA SEISAKUSHO KK
• See references of WO 2018225288A1

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